

# LNJ8L4C18RAA

## Surface Mounting Chip LED

3528 (PLCC4) Type

### Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	190	mW
Forward current	$I_F$	70	mA
Pulse forward current *	$I_{FP}$	100	mA
Reverse voltage	$V_R$	5	V
Junction temperature	$T_j$	125	$^\circ\text{C}$
Thermal resistance	$R_{th}$	130	$^\circ\text{C}/\text{W}$
Operating ambient temperature	$T_{opr}$	-40 to +105	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +125	$^\circ\text{C}$

### Lighting Color

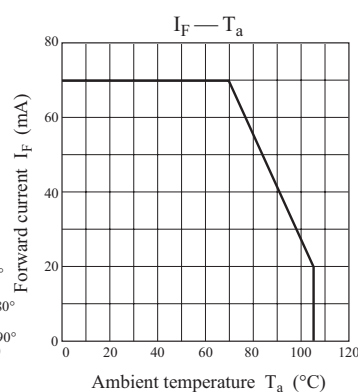
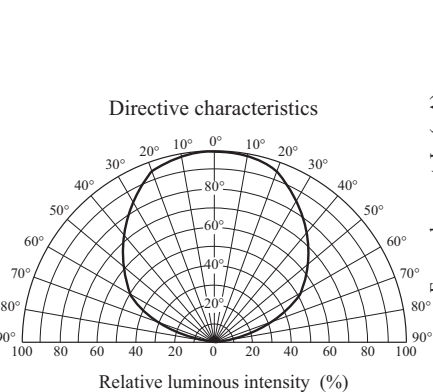
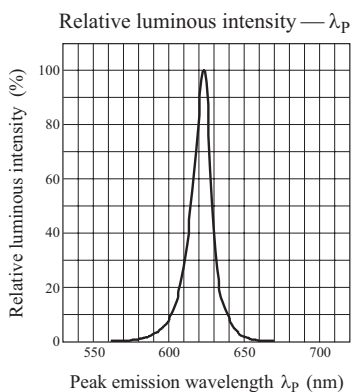
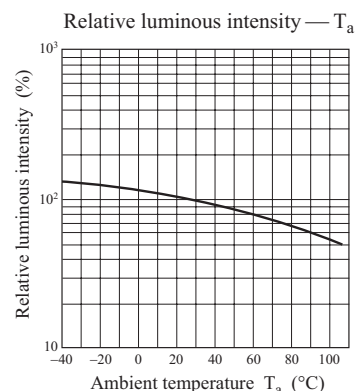
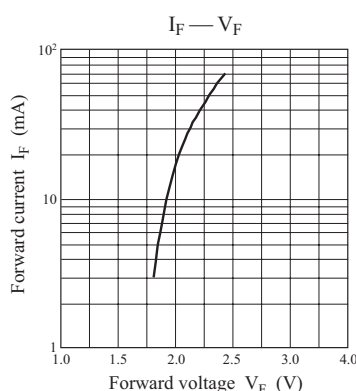
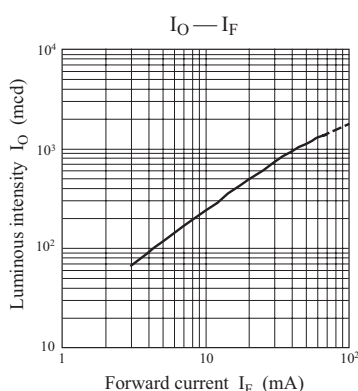
- Red

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

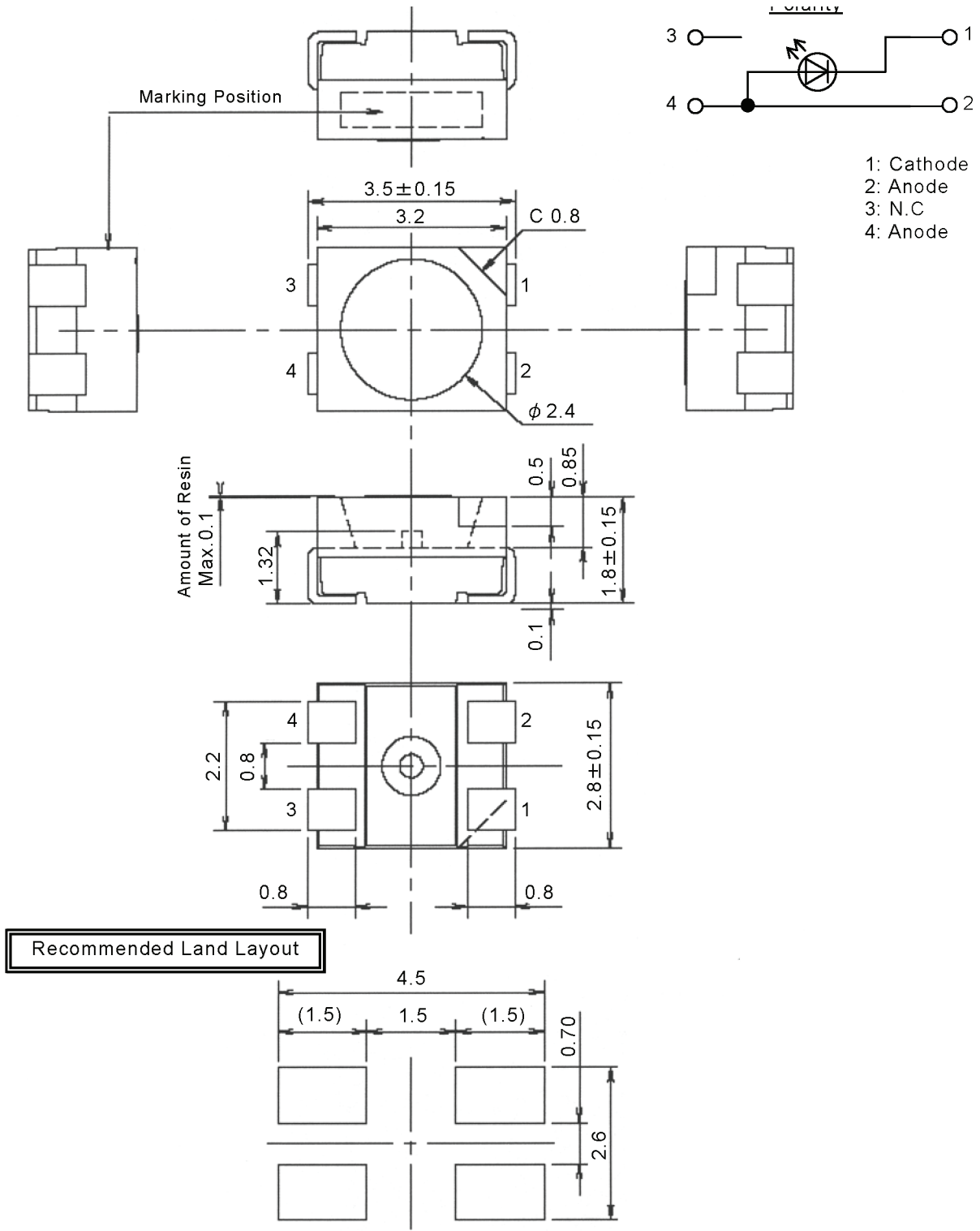
### Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	$I_O$	$I_F = 50 \text{ mA}$	900	1130	1450	mcd
Reverse current	$I_R$	$V_R = 5 \text{ V}$			10	$\mu\text{A}$
Forward voltage *2	$V_F$	$I_F = 50 \text{ mA}$	2.05	2.30	2.65	V
Luminous flux *1	F	$I_F = 50 \text{ mA}$	(3.36)	(4.20)	(5.40)	lm
Peak emission wavelength	$\lambda_p$	$I_F = 50 \text{ mA}$		623		nm
Dominant emission wavelength *3	$\lambda_d$	$I_F = 50 \text{ mA}$	612	617	624	nm
Spectral half band width	$\Delta\lambda$	$I_F = 50 \text{ mA}$		20		nm

Note) \*1: Measurement tolerance:  $\pm 11\%$   
 \*2: Measurement tolerance:  $\pm 0.15 \text{ V}$   
 \*3: Measurement tolerance:  $\pm 2 \text{ nm}$



■ Package (Unit: mm)



(Note1) Tolerance unless specified:  $\pm 0.1$  mm.

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